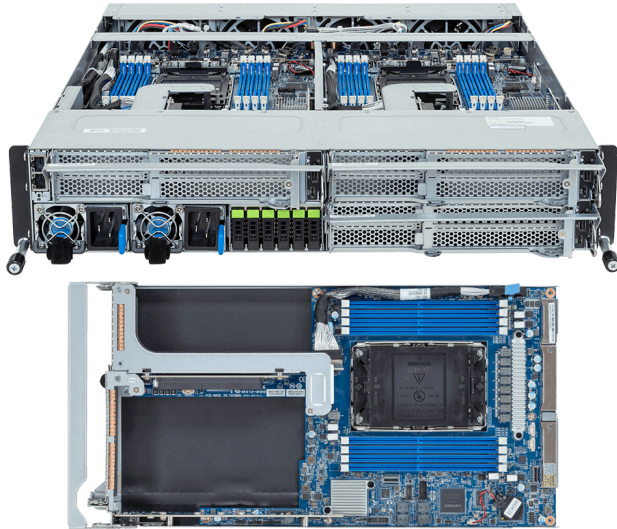


H223-S10-AAP1

High Density Server - 5th/4th Gen Intel® Xeon® Scalable Processors -
2U 3-Node UP 6-Bay E1.S Gen4 NVMe



Key Features

- 2U 3-node front access server system
- Single 5th/4th Gen Intel® Xeon® Scalable processors per node
- Single Intel® Xeon® CPU Max Series per node
- 8-Channel DDR5 RDIMM per CPU with 8 x DIMMs per node
- 2 x CMC ports
- 6 x 9.5mm E1.S Gen4 NVMe hot-swap bays
- 3 x M.2 slots with SATA
- 6 x FHHL PCIe x16 slots with Gen5 x16 lanes
- 3 x LP PCIe x16 slots with Gen5 x16 lanes
- 3 x LP PCIe x16 slots with Gen5 x8 lanes
- 1+1 3000 W 80 PLUS Titanium redundant power supplies

Applications

High-Performance Computing Server, High Converged Server,
Servers for Hybrid/Private Cloud, Edge Server...

Specification

Dimensions	2U 3-Node - Front access (W447.8 x H87.5 x D500 mm)	PCIe Expansion Slots	6 x FHHL x16 (Gen5 x16) 3 x LP x16 (Gen5 x16) 3 x LP x16 (Gen5 x8)
Motherboard	MS13-HD0	I/O Ports	Front: 2 x CMC ports, 1 x CMC status LED, 3 x USB 3.2 Gen1, 3 x Mini-DP
CPU	5th Generation Intel® Xeon® Scalable processors 4th Generation Intel® Xeon® Scalable processors Intel® Xeon® CPU Max Series Single processor per node - With 1 x PCIe card per node at 35°C ambient, TDP up to 350 W - With 2 x PCIe cards per node at 30°C ambient, TDP up to 350 W - With 3 x PCIe cards per node at 35°C ambient, TDP up to 300 W - With 4 x PCIe cards per node at 30°C ambient, TDP up to 300 W	Backplane Board	PCIe Gen4 x4
OS Compatibility	OS Support List	TPM	1 x TPM header (SPI), Optional TPM 2.0 kit: CTM010
Socket	3 x LGA 4677 (Socket E)	Power Supply	1+1 3000 W 80 PLUS Titanium redundant power supplies AC Input: 100-240 V *The system power supply requires C19 power cord.
Chipset	Intel® C741	System Management	ASPEED® AST2600 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface
Memory	8-Channel DDR5 RDIMM, 24 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s [4th Gen Intel Xeon] Up to 4800 MT/s [Intel Xeon Max Series] Up to 4800 MT/s	System Fans	4 x 80x80x38mm
LAN	2 x CMC Management LAN	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Video	Integrated in ASPEED® AST2600 x 3 - 3 x Mini-DP	Packaging Content	1 x H223-S10-AAP1 3 x CPU heatsinks 1 x Mini-DP to D-Sub cable 9 x CPU carriers 1 x L-shape Rail kit
Storage	Front hot-swap: 6 x 9.5mm E1.S Gen4 NVMe Internal M.2: 3 x M.2 (2242/2260/2280/22110), SATA	Ordering Part Numbers	6NH223S10DR000ABP1*
RAID	Onboard VROC key header		



Learn more at: <https://www.gigabyte.com/Enterprise>

* All specifications are subject to change without notice. Please visit our website for the latest information.

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